

Description

The TDM501 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon high speed photo transistor in a plastic SOP5 package.

With the robust coplanar double mold structure, TDM501 series provide the most stable isolation feature.

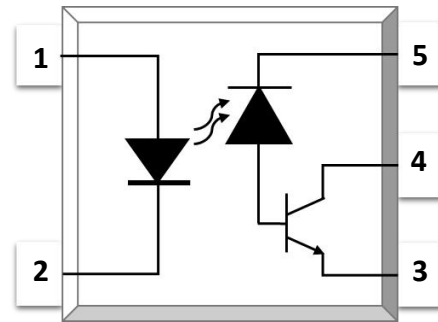
Features

- High isolation 3750 VRMS
- DC input with high speed transistor
- Operating temperature range - 40 °C to 100 °C
- REACH compliance
- Halogen free
- MSL class 1
- Regulatory Approvals
 - UL - UL1577 (Pending Approved)
 - VDE - EN60747-5-5(VDE0884-5)
 - CQC – GB4943.1, GB8898

Applications

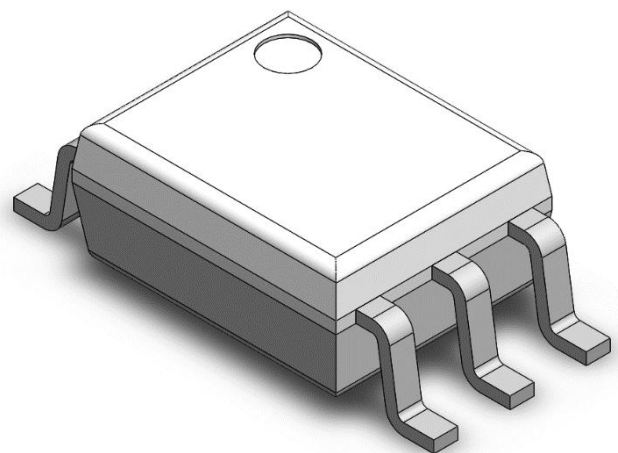
- Line receivers
- Telecommunication equipment
- Out interface to CMOS-LSTTL-TTL
- Wide bandwidth analog coupling
- Pulse transformer replacement
- Computer-peripheral interface

SCHEMATIC



PIN DEFINITION

1.Anode	5.VCC
	4.VO
2.Cathode	3.GND





ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT	Note
INPUT				
Forward Current	I_F	25	mA	
Peak Forward Current	I_{FP}	50	mA	1
Peak Transient Current	$I_{F(trans)}$	1	A	2
Reverse Voltage	V_R	5	V	
Input Power Dissipation	P_I	100	mW	
OUTPUT				
Supply Voltage	V_{CC}	-0.5~30	V	
Output Voltage	V_O	-0.5~20	V	
Output Current	I_o	50	mA	
Output Power Dissipation	P_O	100	mW	
COMMON				
Total Power Dissipation	P_{tot}	200	mW	
Isolation Voltage	V_{iso}	3750	V _{rms}	3
Operating Temperature	T_{opr}	-40~100	°C	
Storage Temperature	T_{stg}	-55~125	°C	
Soldering Temperature	T_{sol}	260	°C	4

Note 1. 50% duty, 1ms P.W

Note 2. $\leq 1\mu s$ P.W, 300pps

Note 3. AC For 1 Minute, R.H. = 40 ~ 60%

Note 4. For 10 seconds



ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C							
PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION	NOTE
INPUT							
Forward Voltage	V_F	-	1.45	1.8	V	$I_F=16mA$	
Reverse Current	I_R	-	-	10	μA	$V_R=5V$	
Input Capacitance	C_{in}	-	60	-	pF	$V=0, f=1MHz$	
OUTPUT							
High Level Supply Current	I_{CCH}	-	0.01	1	μA	$I_F=0mA, V_O=Open, V_{CC}=15V, T_a=25^\circ C$	
		-	-	2	μA	$I_F=0mA, V_O=Open, V_{CC}=15V$	
Low Level Supply Current	I_{CCL}	-	200	-	μA	$I_F=16mA, V_O=Open, V_{CC}=15V$	
Logic High Output Current	I_{OH}	-	0.001	0.5	μA	$I_F=0mA, V_O=V_{CC}=5.5V, T_a=25^\circ C$	
		-	0.01	1	μA	$I_F=0mA, V_O=V_{CC}=15V, T_a=25^\circ C$	
		-	-	50	μA	$I_F=0mA, V_O=V_{CC}=15V$	



ELECTRICAL OPTICAL CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION	NOTE
TRANSFER CHARACTERISTICS(at Ta=0 to 70°C , unless specified otherwise)							
Current Transfer Ratio	CTR	7	-	50	μA	I _F = 16mA ,V _O = 0.4V, V _{CC} =4.5V, Ta=25°C	
Logic Low Output Voltage	V _{OL}	-	0.18	0.4	μA	I _F = 16mA ,I _O = 1.1mA, V _{CC} =4.5V, Ta=25°C	
Isolation Resistance	Riso	10 ¹²	10 ¹⁴	-	Ω	DC500V, 40 ~ 60% R.H.	
Floating Capacitance	C _{IO}	-	0.3	-	pF	V=0, f=1MHz	



CHARACTERISTIC CURVES

Fig.1 Forward Current vs. Forward Voltage

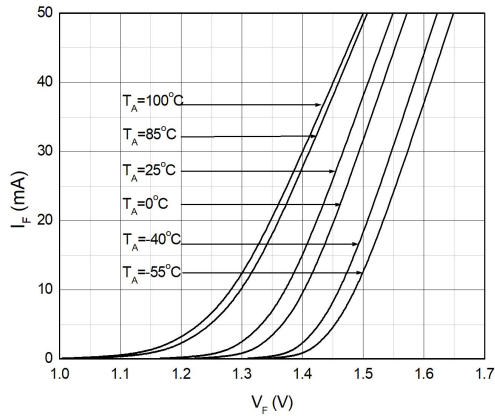


Fig.2 Forward Voltage vs. Ambient Temperature

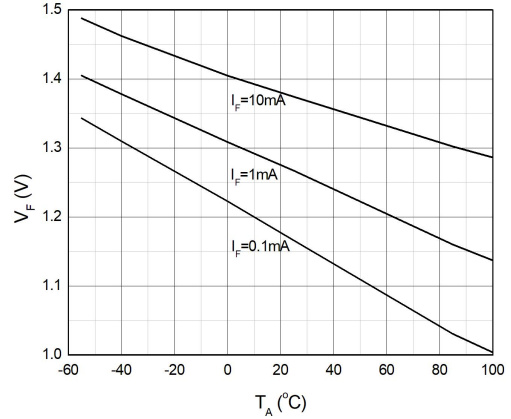


Fig.3 Input Threshold Current vs. Ambient Temperature

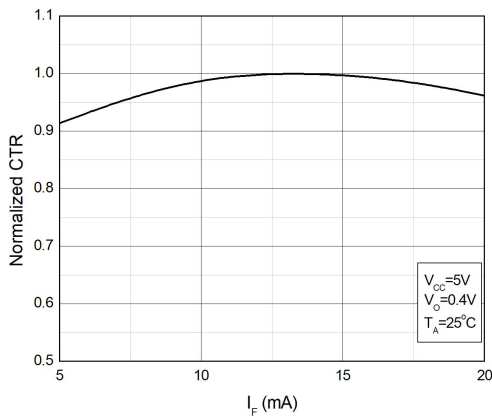


Fig.4 Input Threshold Current vs. Ambient Temperature

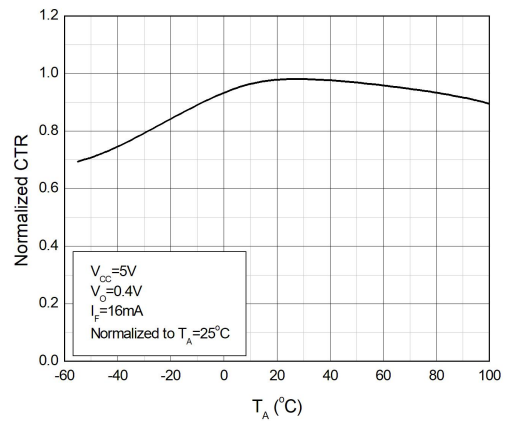


Fig.5 Low Level Output Current vs. Ambient Temperature

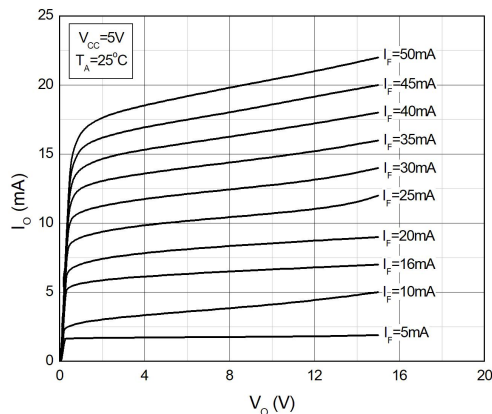
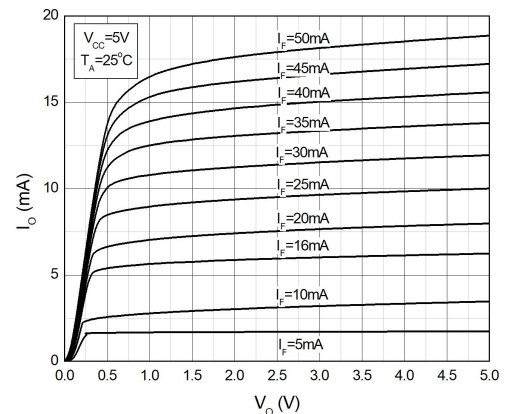


Fig.6 Low Level Output Current vs. Ambient Temperature





CHARACTERISTIC CURVES

Fig.7 Low Level Output Voltage vs. Ambient Temperature

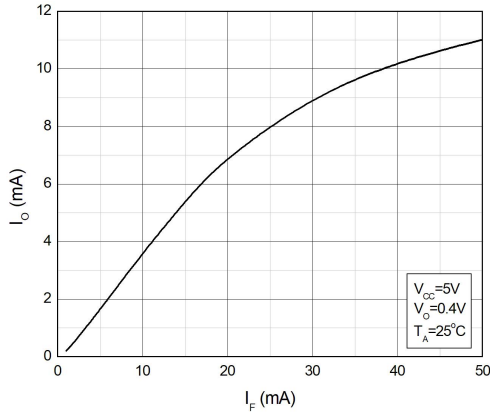


Fig.8 Low Level Output Voltage vs. Ambient Temperature

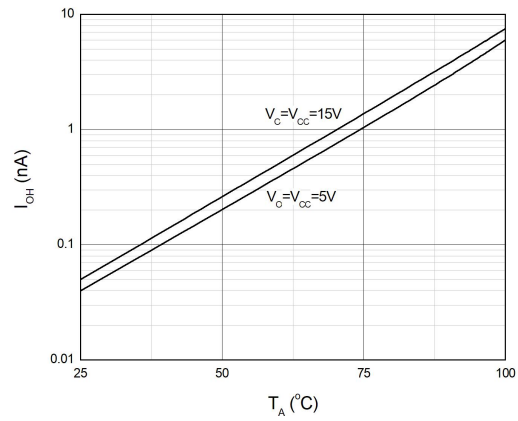


Fig.9 High Level Output Current vs. Ambient Temperature

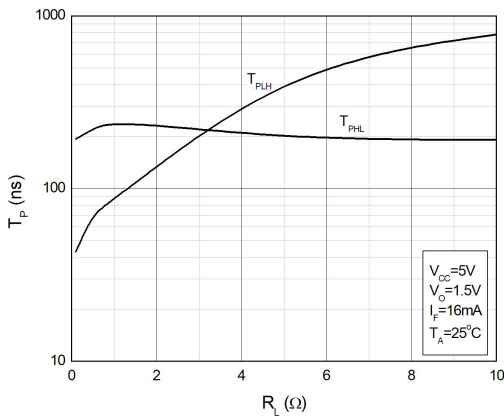


Fig.10 High Level Output Current vs. Ambient Temperature

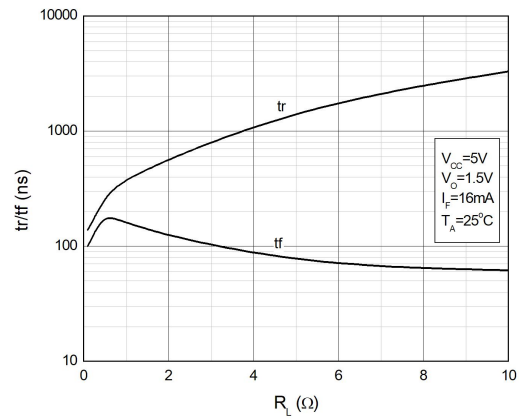


Fig.11 Output Voltage vs. Forward Current

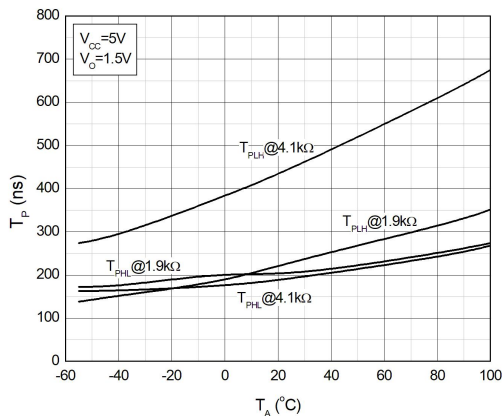
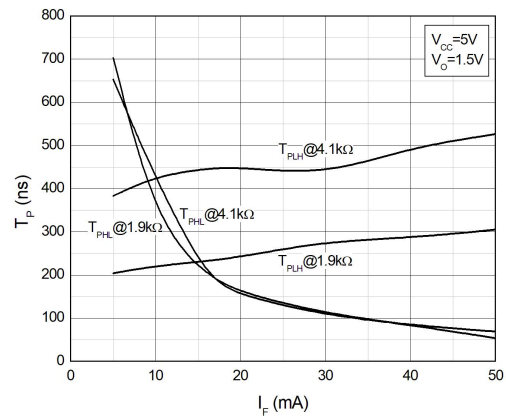


Fig.12 Output Voltage vs. Forward Current



TEST CIRCUITS

Fig.13 Test Circuits for TPHL, TPLH, tr, tf

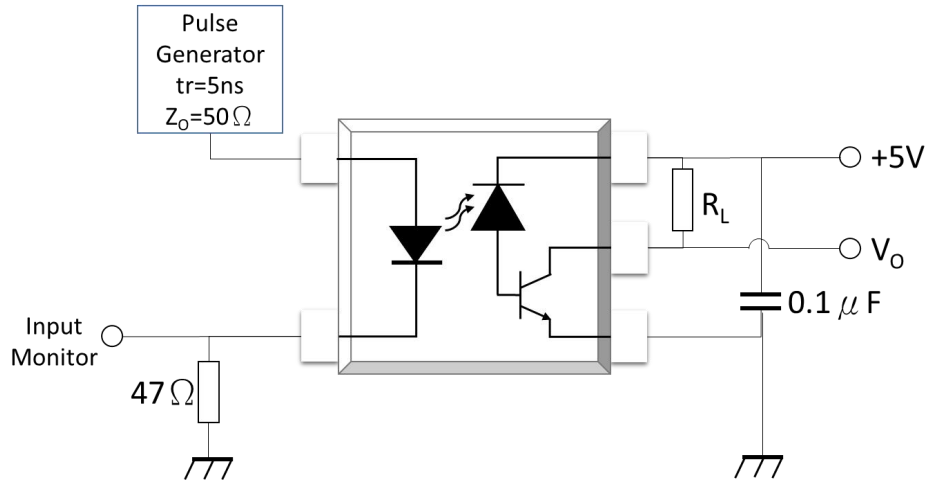
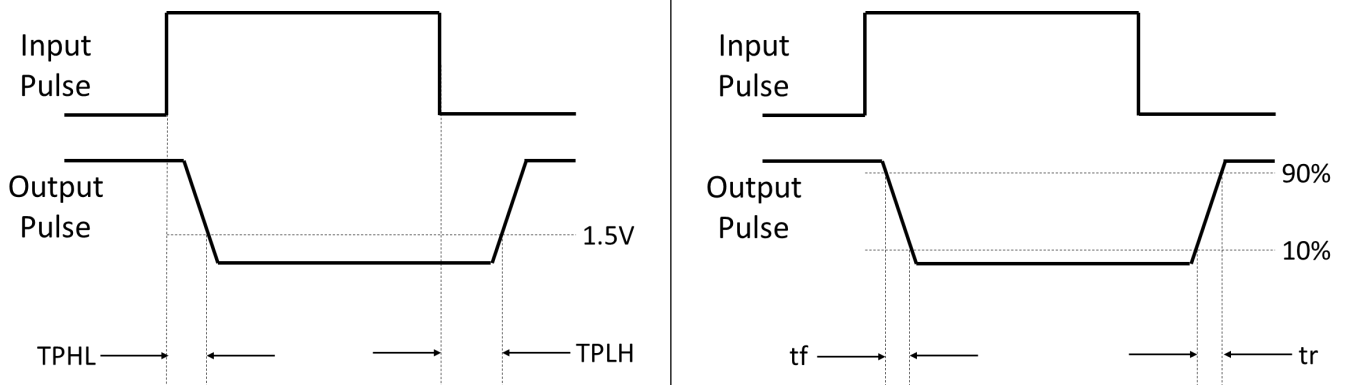


Fig.14 Waveforms of TPHL, TPLH, tr, tf



TEST CIRCUITS

Fig.15 Test Circuits for Common Mode Transient Immunity

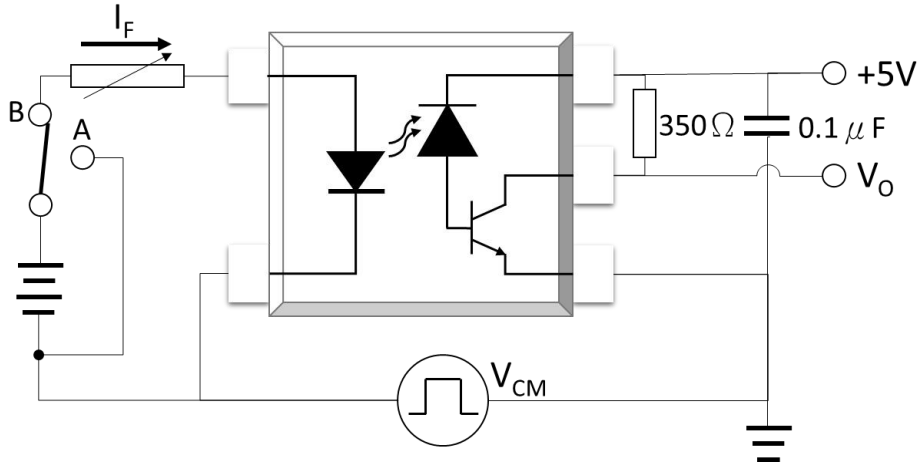
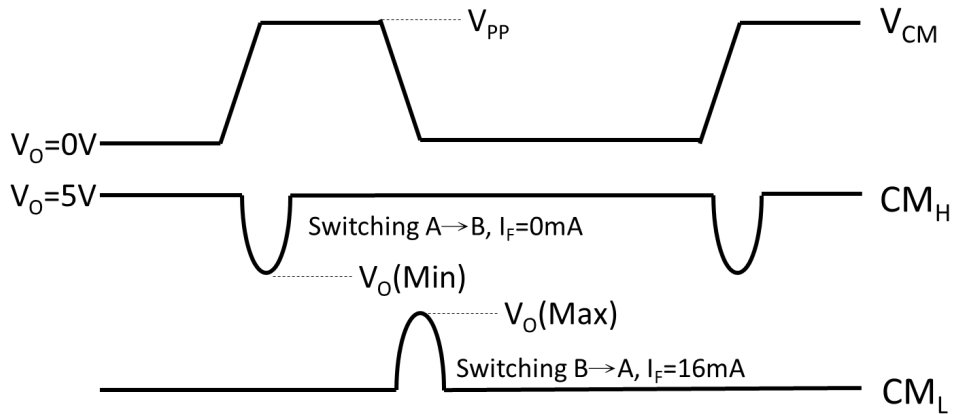
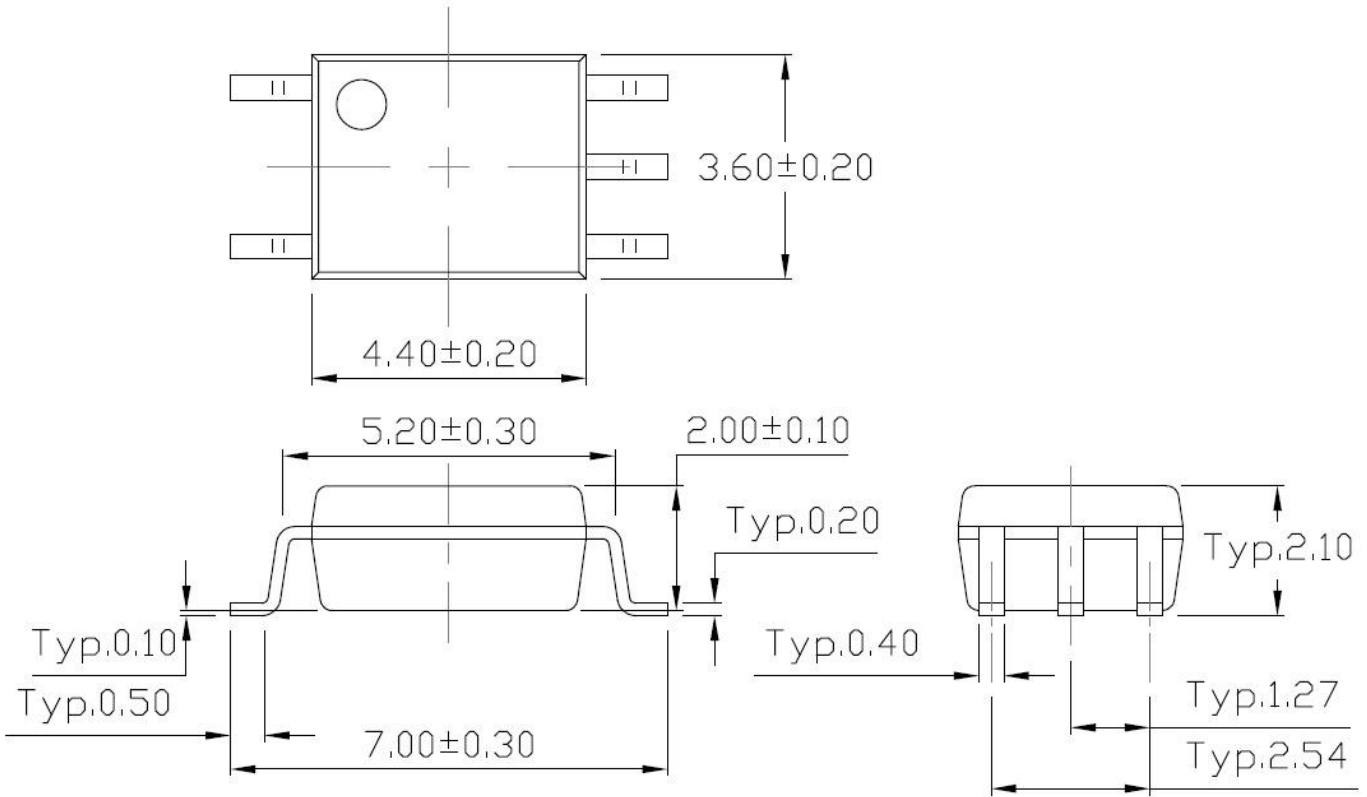


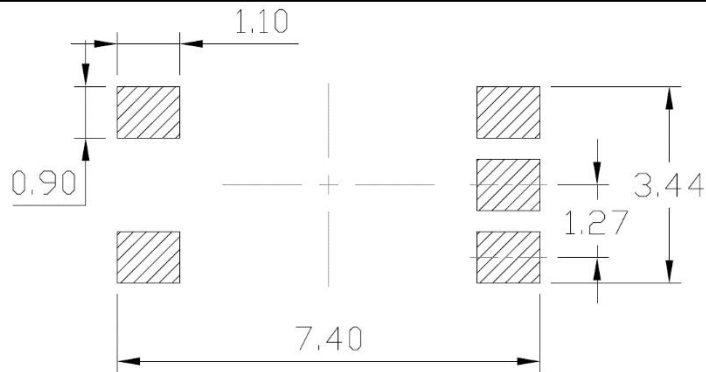
Fig.16 Waveforms of Common Mode Transient Immunity



PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

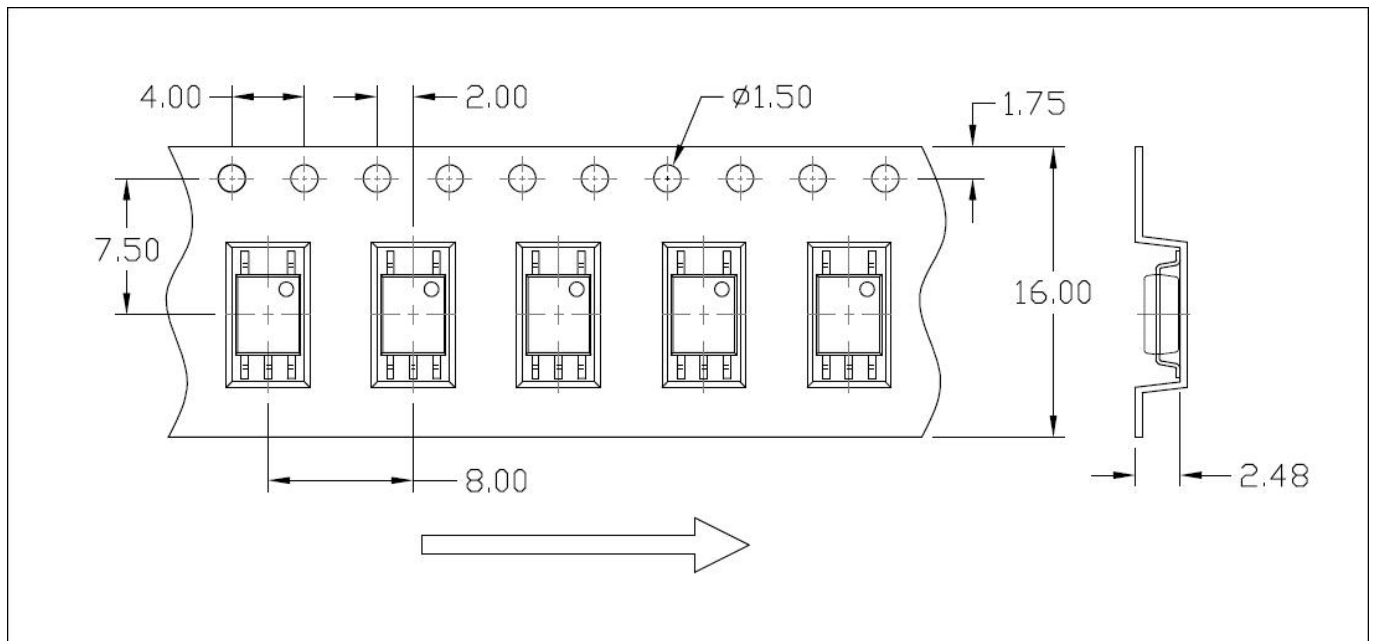


Recommended Solder Mask (Dimensions in mm unless otherwise stated)

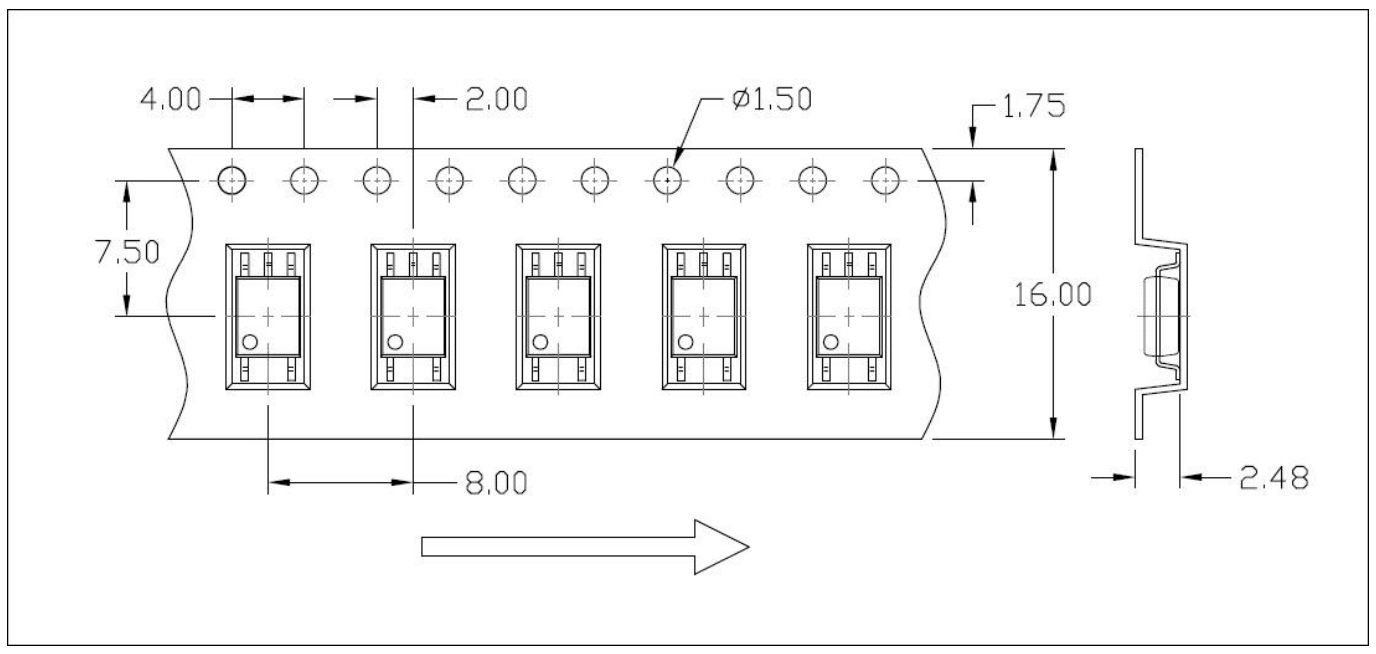


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T1



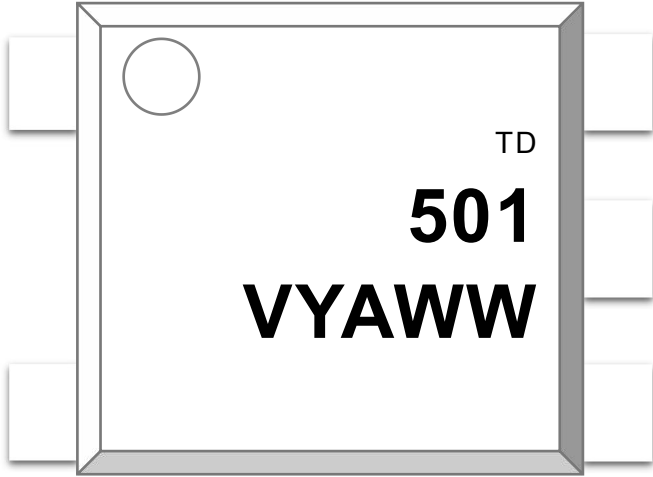
Option T2





ORDERING AND MARKING INFORMATION

MARKING INFORMATION



TD : Company Abbr.
 M501 : Part Number
 V : VDE Option
 Y : Fiscal Year
 A : Manufacturing Code
 WW : Work Week

ORDERING INFORMATION

TDM501(Z)-GV

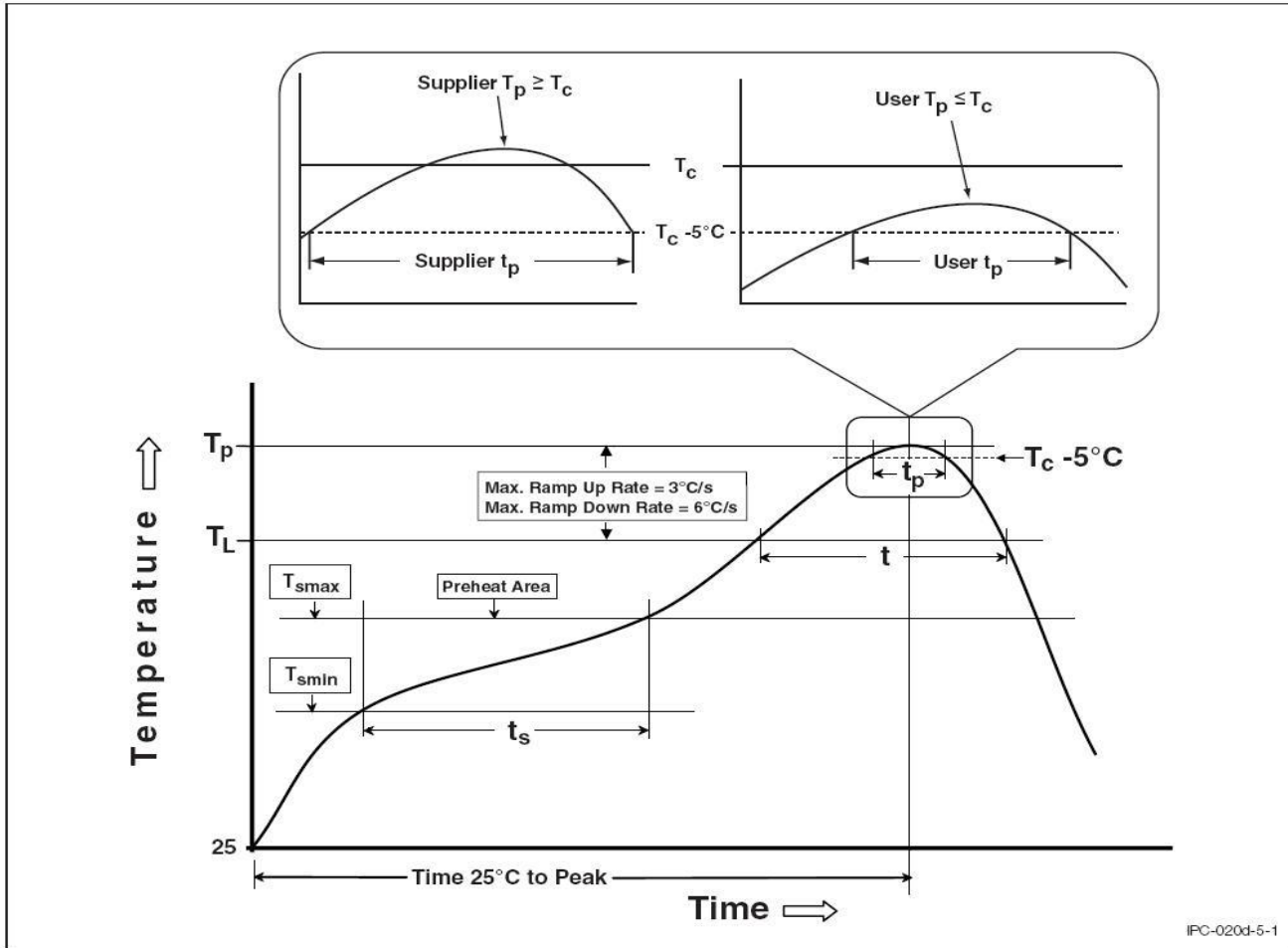
TDM501 – Part Number
 Z – Tape and Reel Option (T1/T2)
 G – Material Option (G: Green, None: Non-Green)
 V – VDE Option (V or None)

PACKING QUANTITY

Option	Description	Quantity
T1	Surface Mount Lead Forming – With Option 1 Taping	3000Units/Reel
T2	Surface Mount Lead Forming – With Option 2 Taping	3000Units/Reel

REFLOW INFORMATION

REFLOW PROFILE



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmmin)	100	150°C
Temperature Max. (Tsmmax)	150	200°C
Time (ts) from (Tsmmin to Tsmmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.	3°C/second max.
Liquidous Temperature (TL)	183°C	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (tP) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



DISCLAIMER

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- The characteristic curves shown in this datasheet are representing typical performance which are not guaranteed.
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- This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or lifesaving applications or any other application which can result in human injury or death.
- Please contact LIGHTNING sales agent for special application request.
- Immerge unit's body in solder paste is not recommended.
- Parameters provided in datasheets may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated in each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify LIGHTNING's terms and conditions of purchase, including but not limited to the warranty expressed therein.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.